CSL® PRODUCT INFORMATION

CSL 506

Electronic Self-Leveling Silicone Sealant/ Adhesive

TYPICAL PROPERTIES	
Uncured	
Type	One-part, RTV
Appearance	Smooth, thick liquid
Specific Gravity	1.02-1.04
Extrusion Rate, 3.2mm (1/8") orifice 6.3 kg/cm^2 (90lb/in^2), g/min	50
Application Temperature Range, °C (°F)	-18 to 50 (0 to 120)
Cure System	Oxime, moisture cure
Skin-over Time at Standard Conditions*, min	30
Cure Time at Standard Conditions*, hour	24
Slump/Sag	Flowable
Cured - at Standard Conditions* for 7 days	
Durometer Hardness (ASTM D2240, Shore A), points	18
Tensile Strength (ASTM D412), kg/cm^2 (psi)	11(150)
Elongation at Break (ASTM D412), %	400
Thermal Expansion Coefficient, cm/cm/°C 0 to 100°C (32 to 212 °F)	9.0×10^{-4}
Tear Resistance (ASTM D624, Die B), kN/m (ppi)	2.5(14)
Temperature Range, °C (°F)	-62 to 232 (-80 to 450)
Dielectric Strength (ASTM D149), V/mil	500(197)
Volume Resistivity (ASTM D257), ohm/cm	2.2×10^{15}
Dissipation Factor (ASTM D150), 100Hz to 100kHz	0.0008
Dielectric Constant (ASTM D150), 100Hz to 100kHz	2.71

*Standard Conditions are 25°C(77°F) and 50% relative humidity.

* Recognized under the Components Program of Underwriters Laboratories Inc.

Can be used where corrosion of metal such as copper, brass and silver might be a problem.

Supplied ready-to-use having excellent unprimed adhesion to a wide variety of substrates.

SL 506 is a one-part, RTV (Room Temperature ulcanizing) Electronic Grade Self-leveling Silicone ealant/Adhesive. No acetic acid or other corrosive by-oducts are generated during its cure. CSL 506 can be ed in corrosion-sensitive electronic equipment with no verse effect.

YPICAL APPLICATIONS

SL 506 is primarily used in applications where a wable, self-leveling silicone sealant/adhesive is required fill small spaces. Applications include potting electrical minals and sealing electronic devices. Since CSL 506 is 100% silicone sealant/adhesive, it resists weathering, isture, vibration, ozone, ultra-violet rays and nperature extremes. CSL 506 remains flexible from to 232 °C (-80 to 450 °F).

RECTIONS

SL 506 is ready-to-use and requires no mixing or ditives. The cure mechanism begins as soon as the sealant comes in contact with air. Uncured sealant will flow until a cured skin is formed

At 25°C (77°F) and 50% relative humidity (R.H.), the sealant will "skin" within 30 minutes and fully cure in 24 hours. Higher humidity accelerates cure. Since no undesirable odors are released during cure, CSL 506 is ideal where applications must be done under confined conditions. Adequate ventilation should be provided with extensive use of this product. In applications where partial or total confinement of sealant is prevalent, the time required for proper cure is generally lengthened by the degree of confinement.

All surfaces should be clean and dry. It is recommended that bonding surfaces be wiped with a solvent such as naphtha. Do not use oil-containing solvents such as varsol. Allow surface to dry thoroughly before applying sealant. Priming is normally not required for applications to most substrates. Unprimed adhesion can be readily tested by applying a small trial flow and allowing 7 days for maximum adhesion to occur.